

US00D830321S

(12) **United States Design Patent**
Podubni

(10) **Patent No.:** **US D830,321 S**

(45) **Date of Patent:** **** Oct. 9, 2018**

(54) **MODULAR CIRCUIT BOARD**

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(73) Assignee: **TinyPCB, Inc.**

(**) Term: **15 Years**

(21) Appl. No.: **29/605,712**

(22) Filed: **May 30, 2017**

(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**

USPC **D13/182**

(58) **Field of Classification Search**

USPC D13/182; 174/68.1, 250, 253, 255, 256;
318/567, 568.1; 361/600, 601, 718, 719,
361/720, 728, 736, 748, 751, 752, 760,
361/761, 807; 439/55, 65, 68, 76.1, 92,
439/93, 95

CPC H05K 3/00; H05K 3/30; H05K 3/301;
H05K 3/303; H05K 3/34; H05K 3/3405;
H05K 3/341; H05K 3/36; H05K 3/361;
H05K 3/363; H05K 3/40; H05K 7/14;
H05K 7/1422; H05K 7/00; H05K 1/18;
H05K 1/02; H05K 1/181; H05K 1/182;
H05K 1/183; H05K 1/184; H05K 1/189;
H05K 1/00

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;

FIG. 2 is a bottom perspective view thereof;

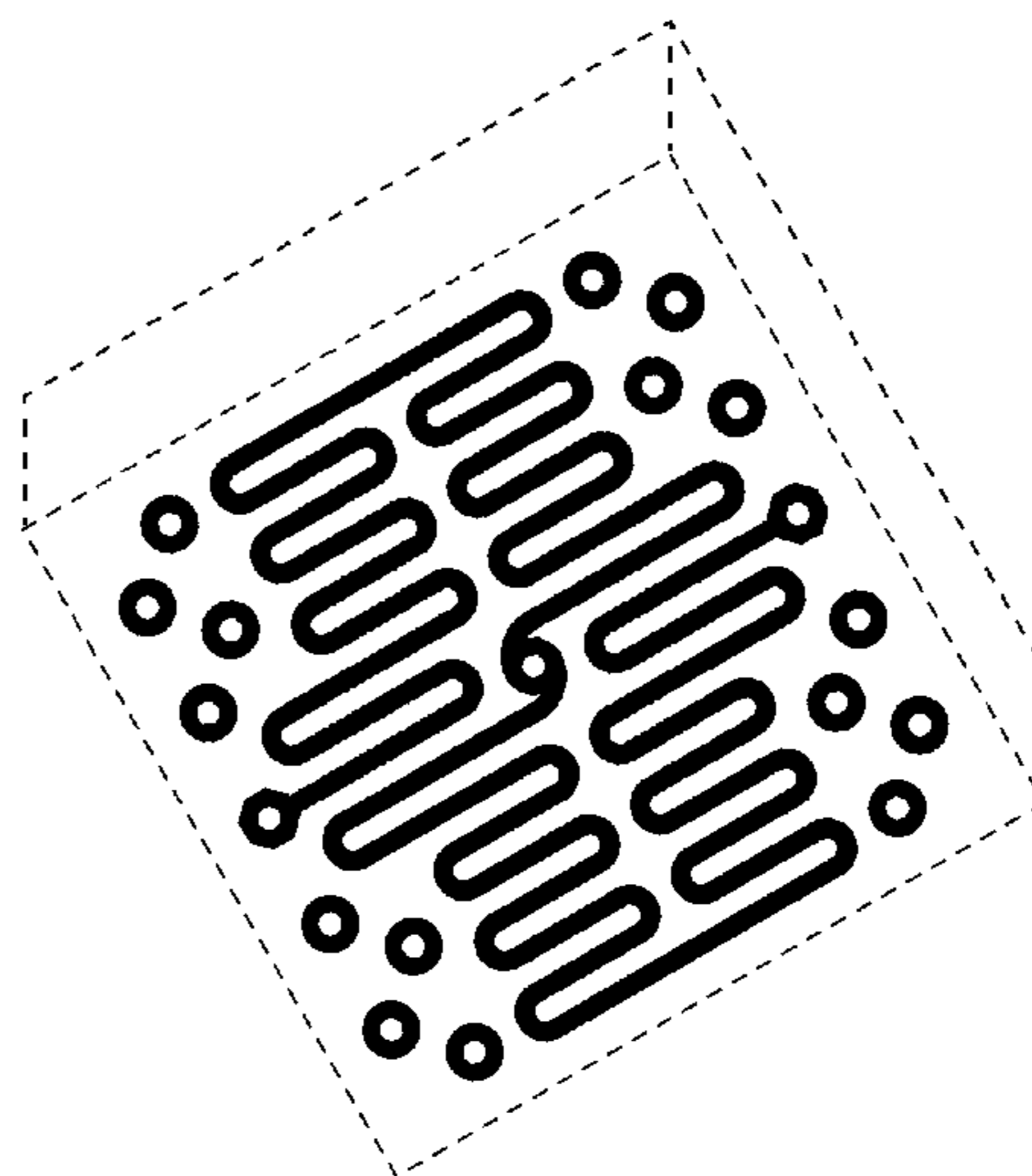
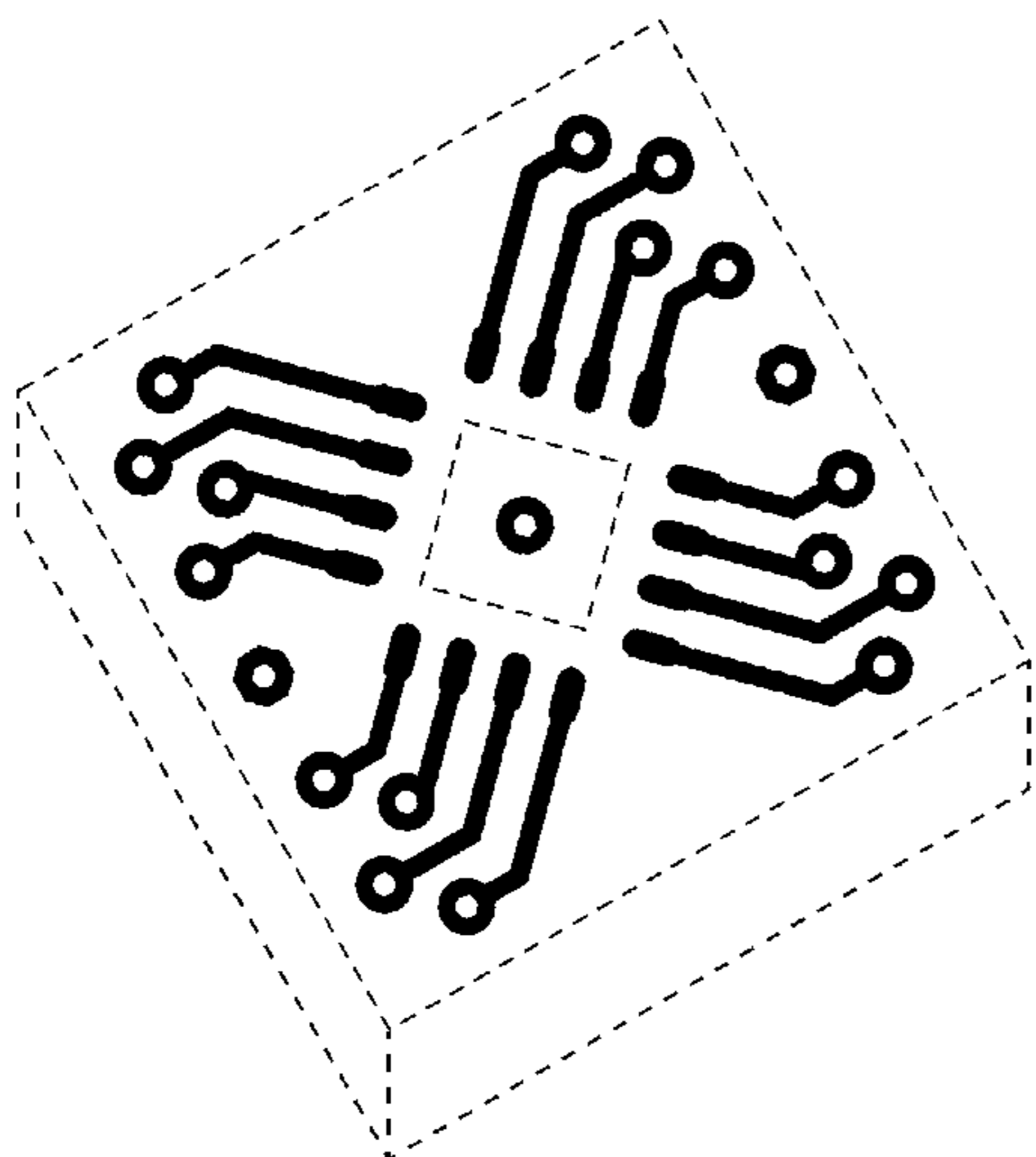
FIG. 3 is a top view thereof;

FIG. 4 is a bottom view thereof; and,

FIG. 5 is a side view thereof, all other side views being a mirror image thereof.

The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets



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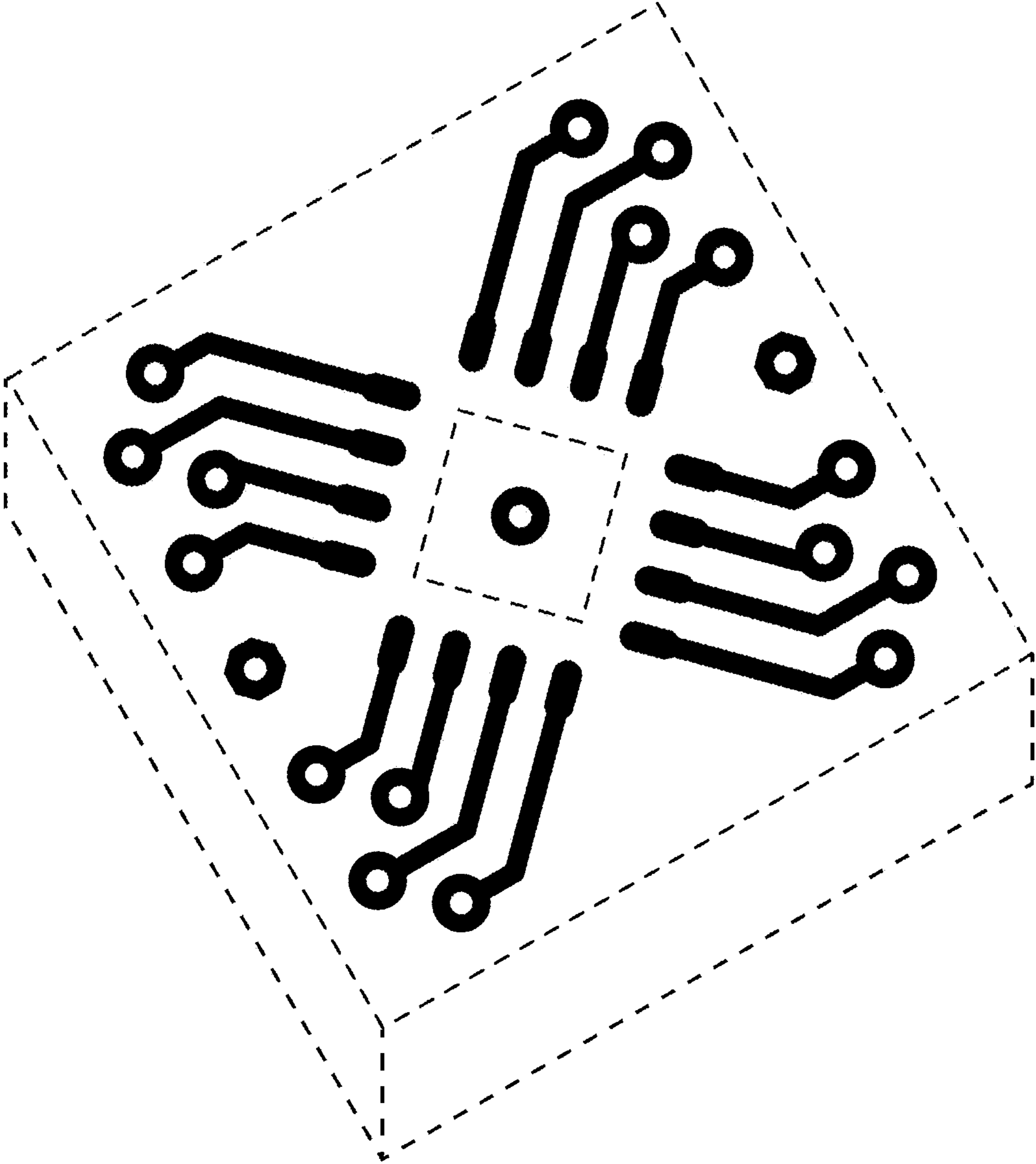


FIG. 1

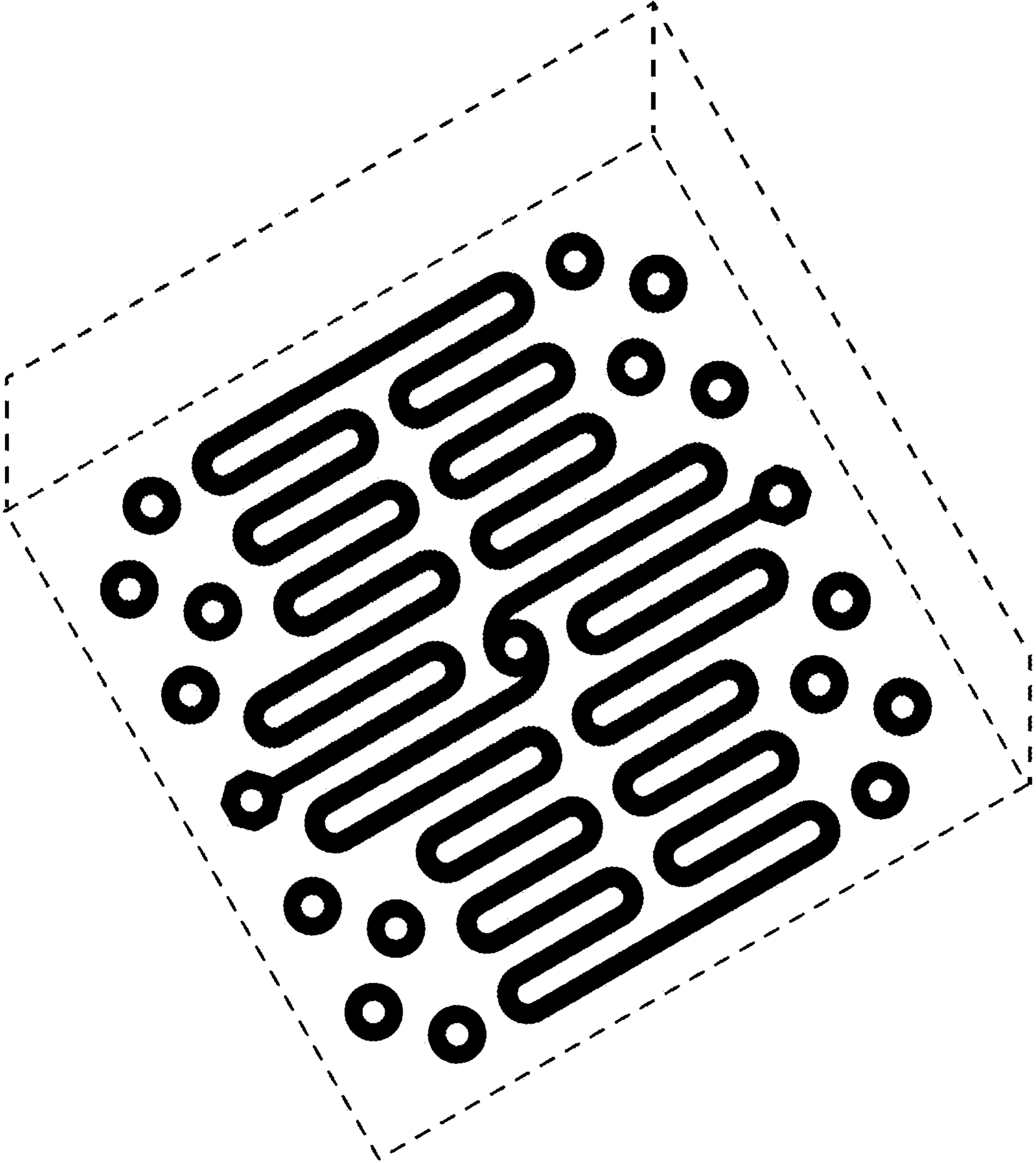


FIG. 2

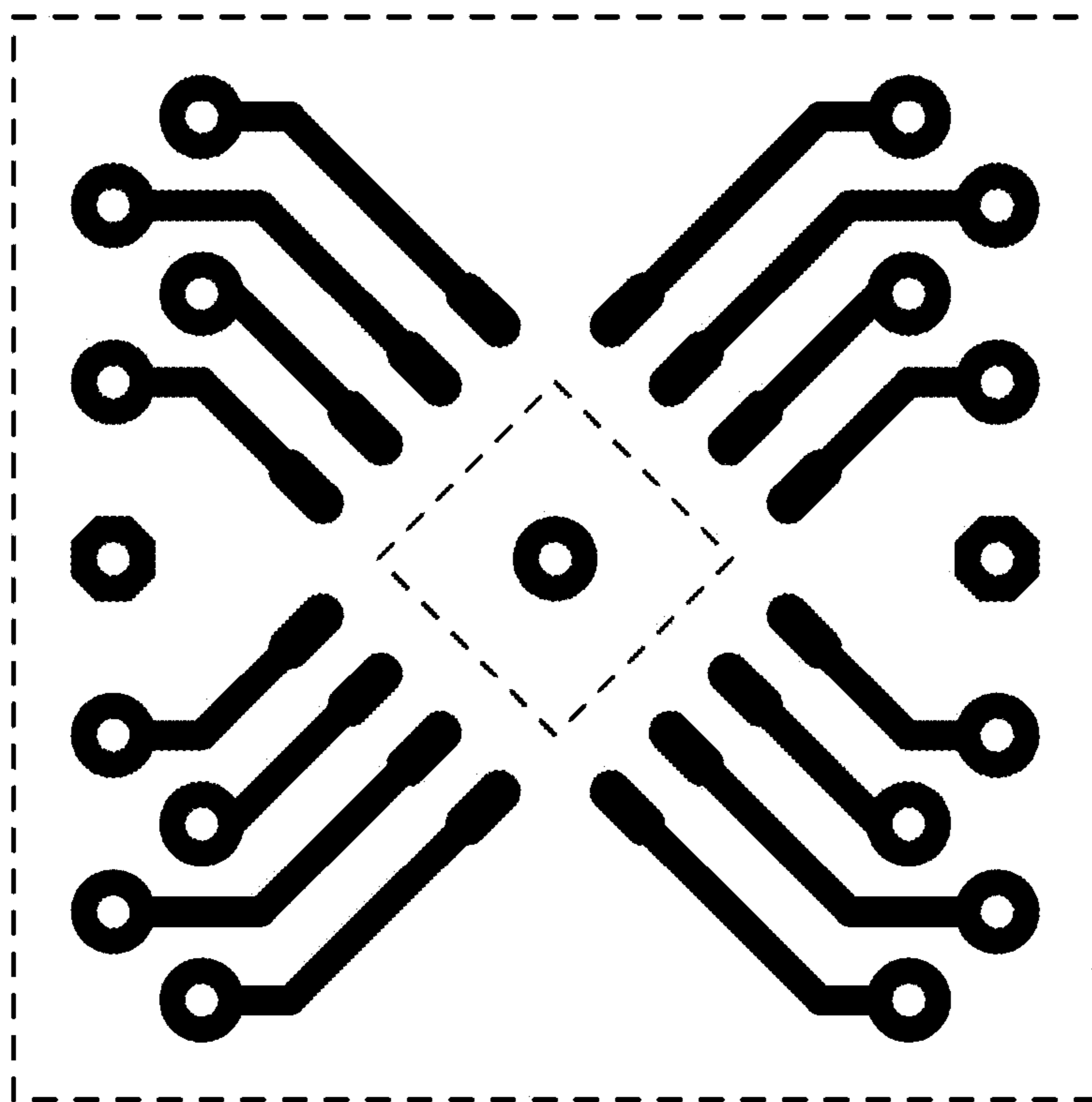


FIG. 3

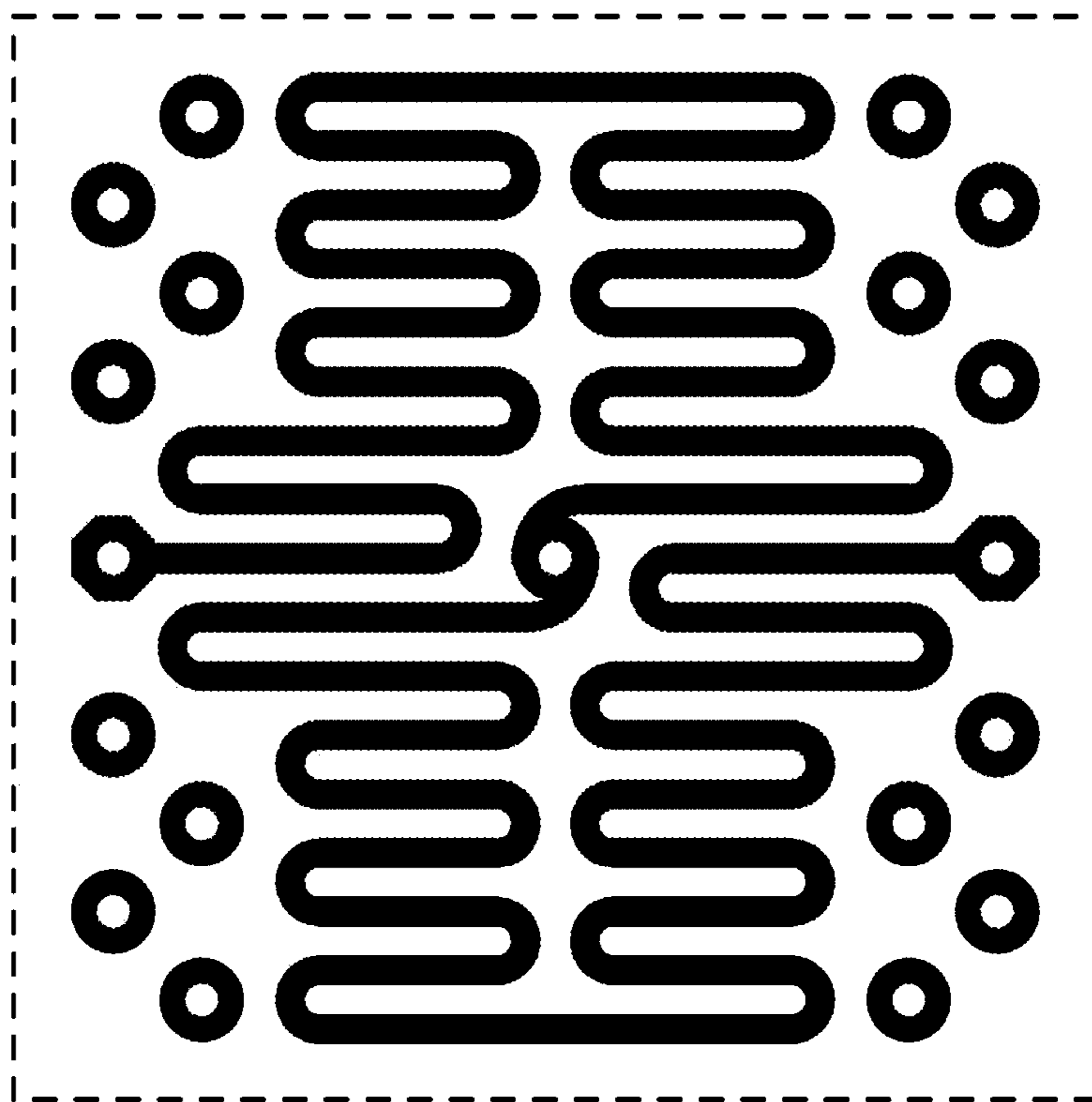


FIG. 4

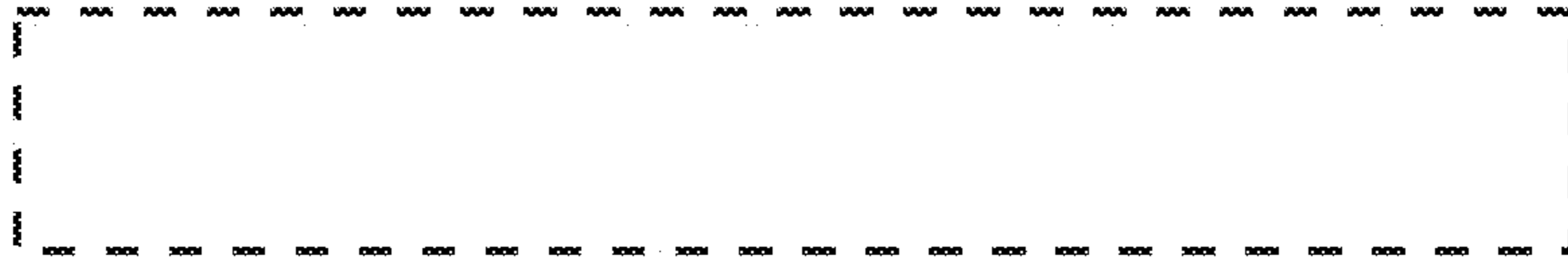


FIG. 5